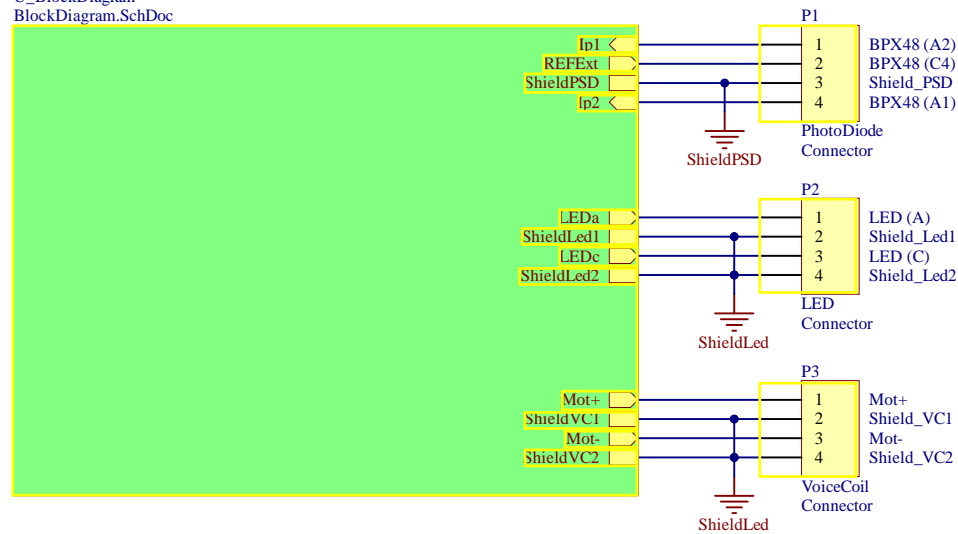

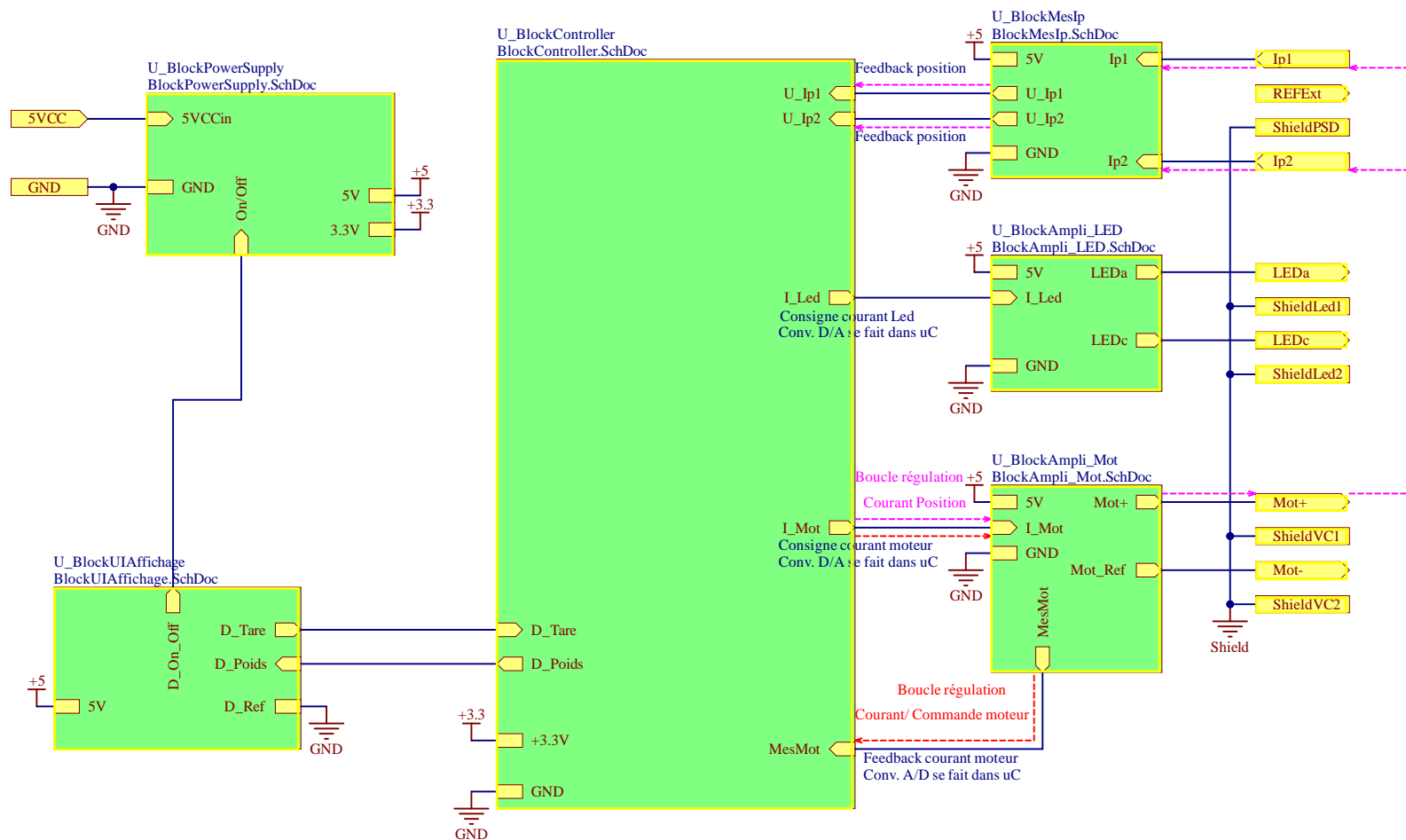
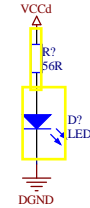
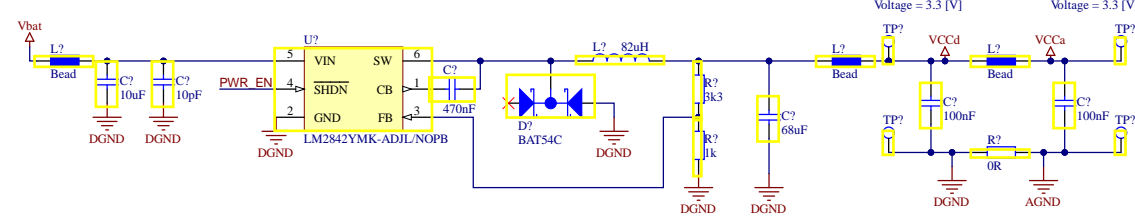
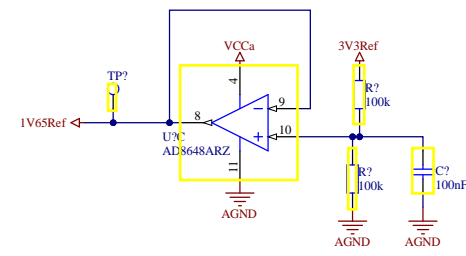
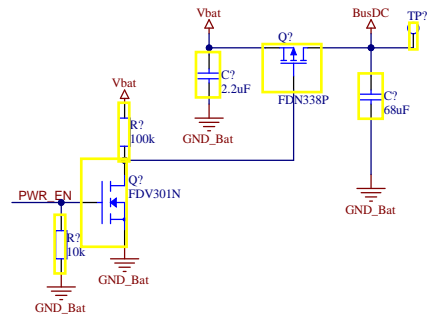
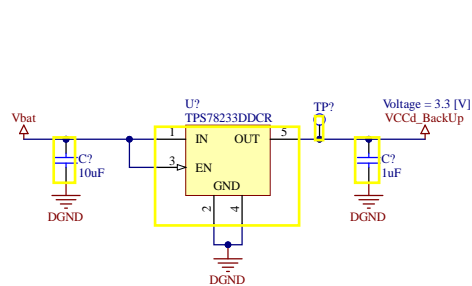


U\_BlockDiagram  
BlockDiagram.SchDoc

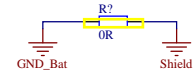
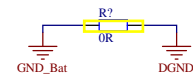
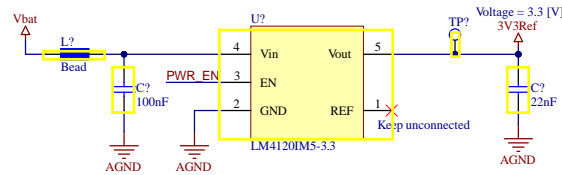
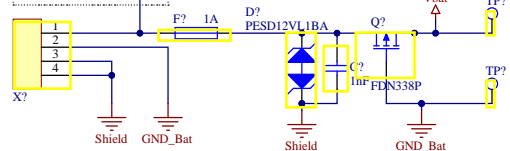
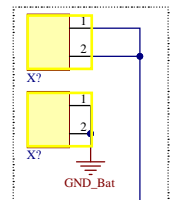


Institut d'automatisation industrielle rte de Cheseaux 1 CH-1401 Yverdon-les-Bains T +41(0)24 55 77 377 F +41(0)24 55 76 320 <a href="http://iai.heig-vd.ch">http://iai.heig-vd.ch</a> <a href="mailto:iai@heig-vd.ch">iai@heig-vd.ch</a>				
Title <b><i>Main_PCB</i></b>				
Size:	Project:	No.	SVN	Version
A4	Balance	N° SGX	OUI	1.0.0
Date:	10.04.2021	Sheet 1 of 8	Author:	BKO + PKI
File: Main_PCB.SchDoc				





Banana connectors to connect a laboratory power supply



Institut d'automatisation industrielle rte de Cheseaux 1 CH-1401 Yverdon-les-Bains T +41(0)24 55 77 377 F +41(0)24 55 76 320 http://iai.heig-vd.ch iai@heig-vd.ch					
Title <b>Block_PowerSupply</b>					
Size: A3	Project: Balance	No. N° SGX	SVN OUI	Version 1.0.0	
Date: 10.04.2021	Sheet 3 of 8	Author: BKO + PKI			
File: BlockPowerSupply_SchDoc					

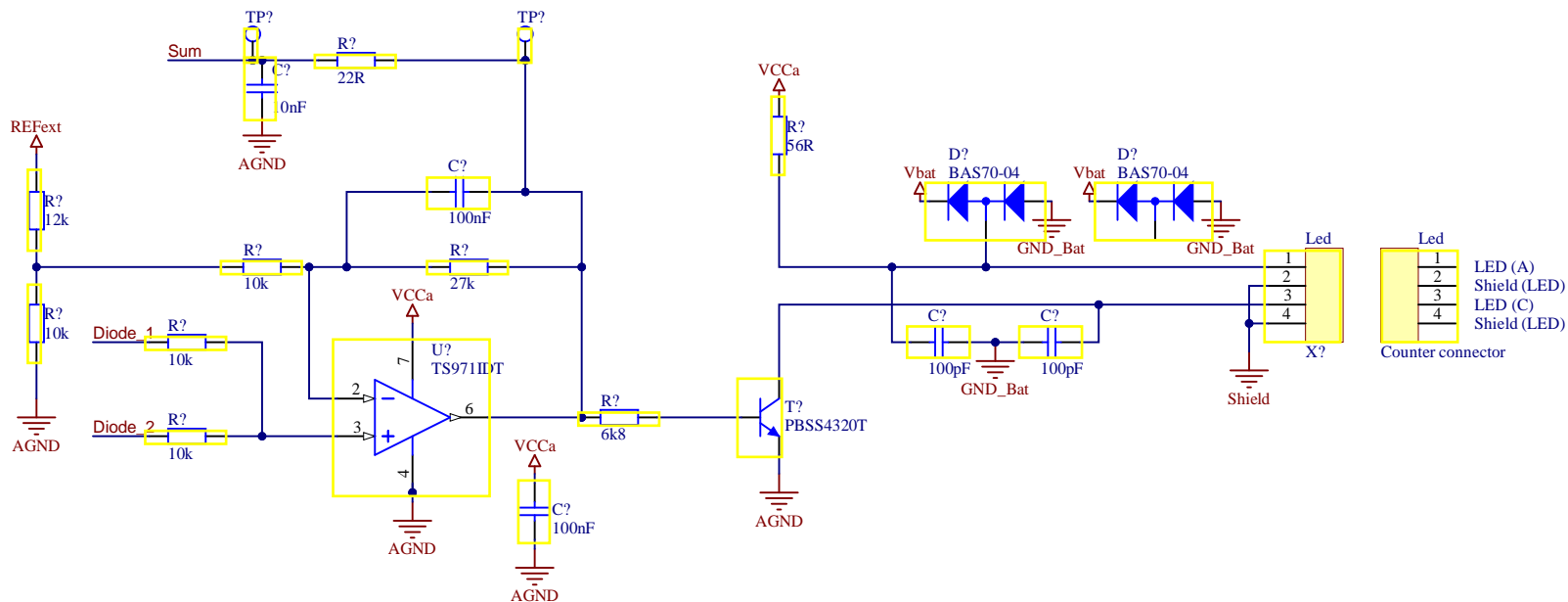


1

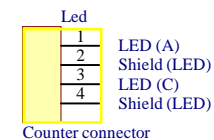
2

3

4



Add Mech\_LED  
component from the library  
and wire it correctly



Institut d'automatisation industrielle  
rte de Cheseaux 1  
CH-1401 Yverdon-les-Bains  
T +41(0)24 55 77 377 F +41(0)24 55 76 320  
<http://iai.heig-vd.ch> [iai@heig-vd.ch](mailto:iai@heig-vd.ch)



Title **Block\_Ampli\_LED**

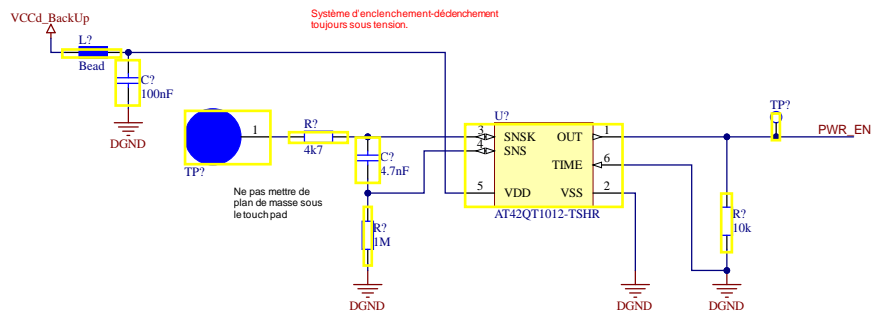
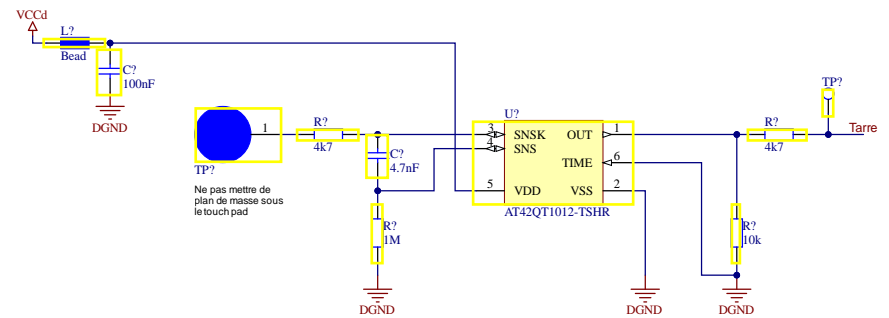
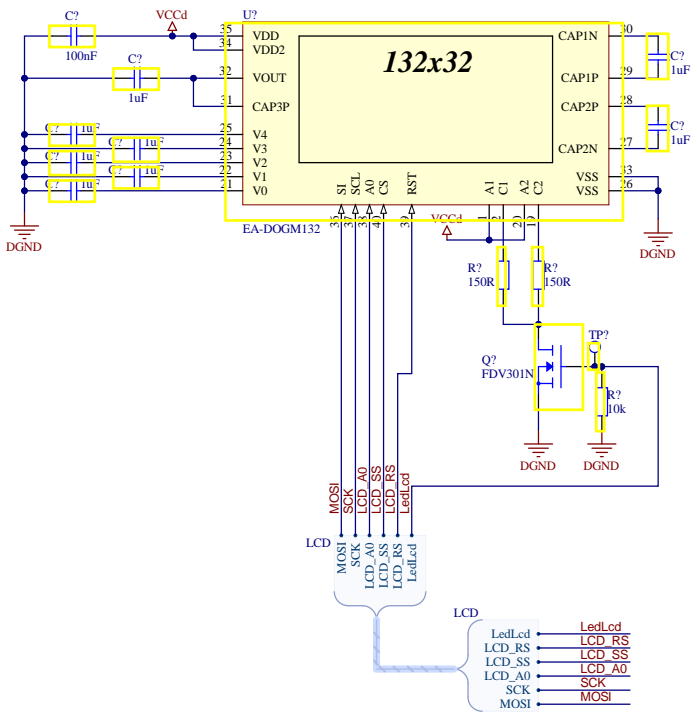
Size: A4	Project: Balance	No. N° SGX	SVN OUI	Version 1.0.0
Date: 10.04.2021	Sheet 5 of 8	Author: BKO + PKI		
File: BlockAmpli_LED.SchDoc				

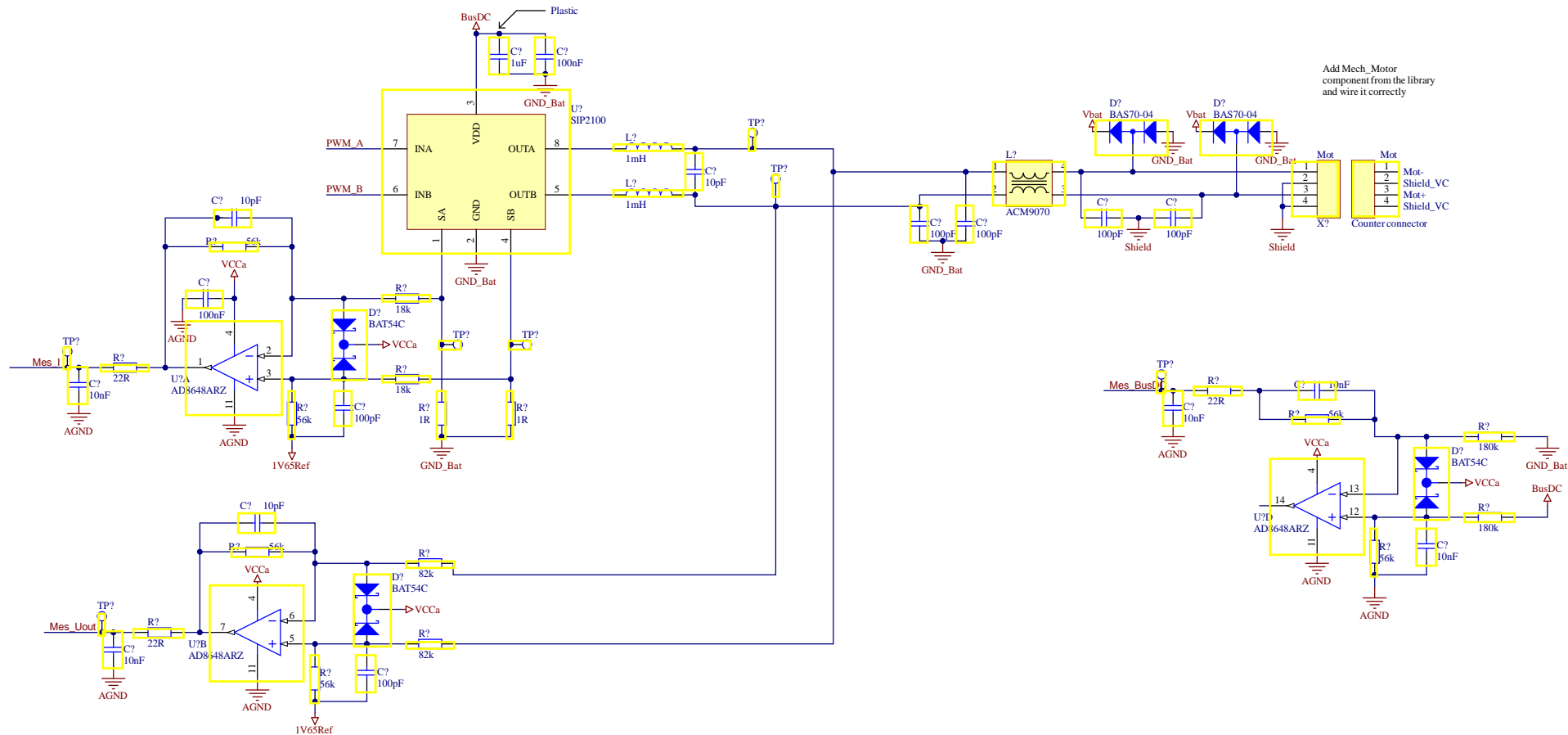
1

2

3

4





Add Mech\_Motor component from the library and wire it correctly

Institut d'automatisation industrielle  
rte de Cheseaux 1  
CH-1401 Yverdon-les-Bains  
T +41(0)24 55 77 377 F +41(0)24 55 76 320  
http://iai.heig-vd.ch iai@heig-vd.ch



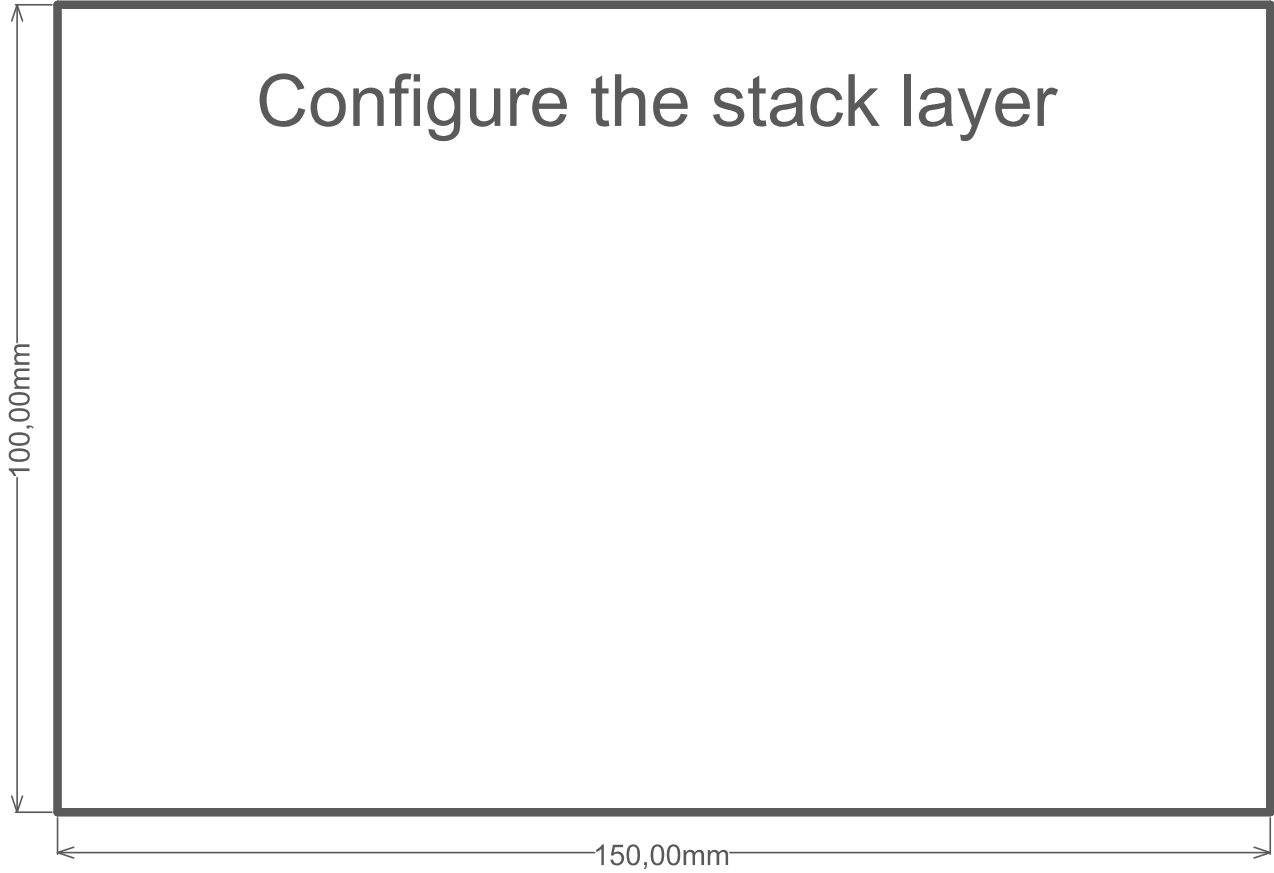
Title **Block\_Ampli\_Moteur**

Size: A3	Project: Balance	No. N° SGX	SVN OUI	Version 1.0.0
Date: 10.04.2021	Sheet 7 of 8	Author: BKO + PKI		
File: BlockAmpli_Mot.SchDoc				

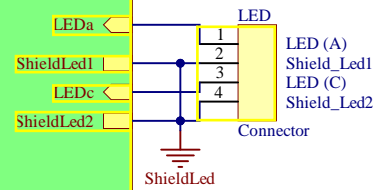




Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
	Top Surface Finish	Nickel, Gold	0.020mm		
	Top Layer	CF-004	0.035mm		
1	Dielectric 1	PP-017	0.129mm	4,3	
	Dielectric 2	PP-017	0.129mm	4,3	
2	Int1 (GND)	CF-004	0.035mm		
	Dielectric 3	Core-039	0.711mm	4,8	
3	Int2 (PWR)	CF-004	0.035mm		
	Dielectric 4	PP-017	0.129mm	4,3	
	Dielectric 5	PP-017	0.129mm	4,3	
4	Bottom Layer	CF-004	0.035mm		
	Bottom Surface Finish	Nickel, Gold	0.020mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				



U\_BlockDiagram  
BlockDiagram.SchDoc

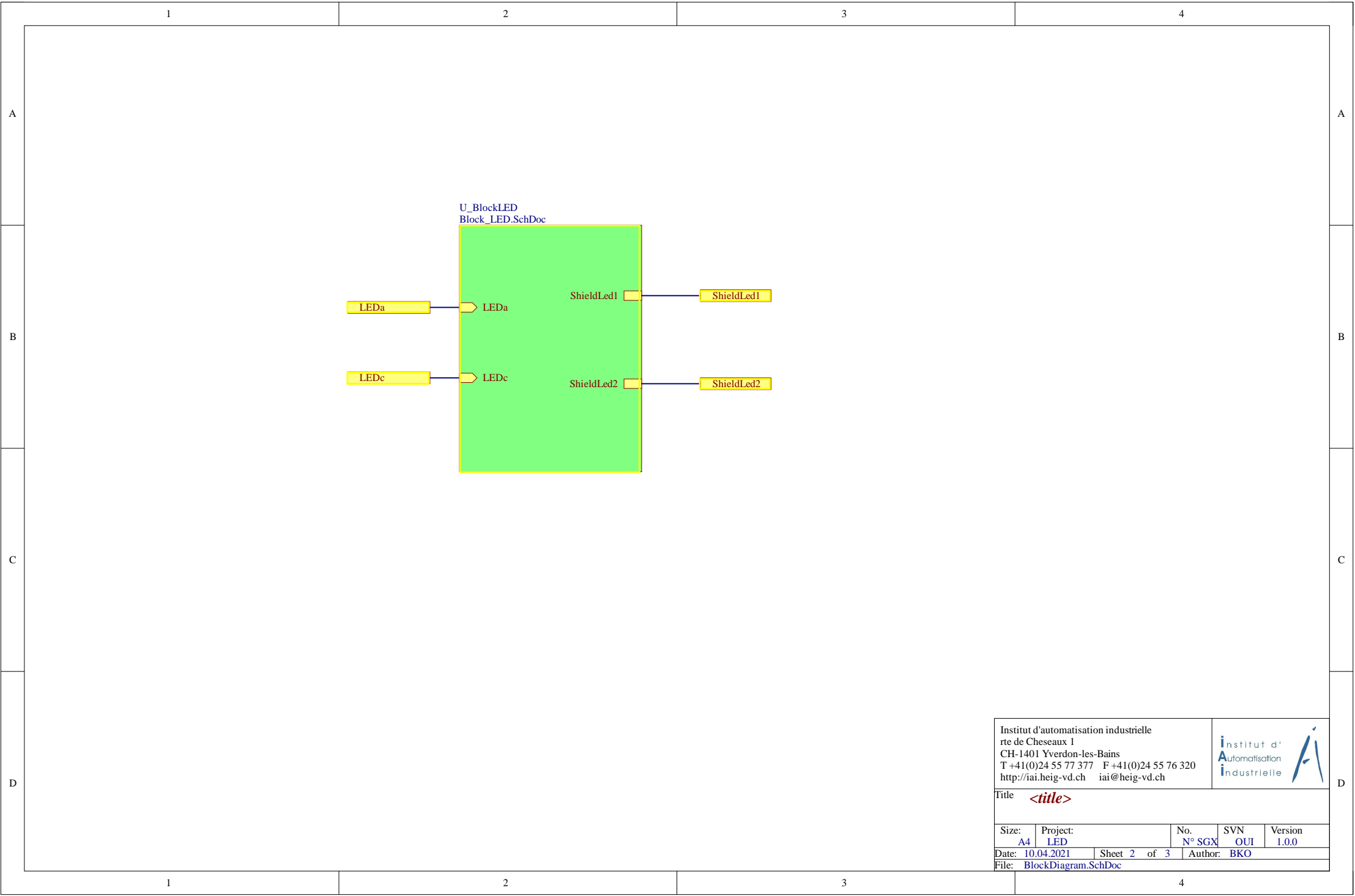


Institut d'automatisation industrielle  
rte de Cheseaux 1  
CH-1401 Yverdon-les-Bains  
T +41(0)24 55 77 377 F +41(0)24 55 76 320  
<http://iai.heig-vd.ch> [iai@heig-vd.ch](mailto:iai@heig-vd.ch)



Title *<title>*

Size: A4	Project: LED	No. N° SGX	SVN OUI	Version 1.0.0
Date: 10.04.2021	Sheet 1	of 3	Author: BKO	
File: LED.SchDoc				



1

2

3

4

A

A

B

B

C

C

D

D

Institut d'automatisation industrielle  
rte de Cheseaux 1  
CH-1401 Yverdon-les-Bains  
T +41(0)24 55 77 377 F +41(0)24 55 76 320  
<http://iai.heig-vd.ch> [iai@heig-vd.ch](mailto:iai@heig-vd.ch)



Title *<title>*

Size:	Project:	No.	SVN	Version
A4	LED	N° SGX	OUI	1.0.0

Date:	10.04.2021	Sheet	3	of	3	Author:	BKO
-------	------------	-------	---	----	---	---------	-----

File: [Block\\_LED.SchDoc](#)

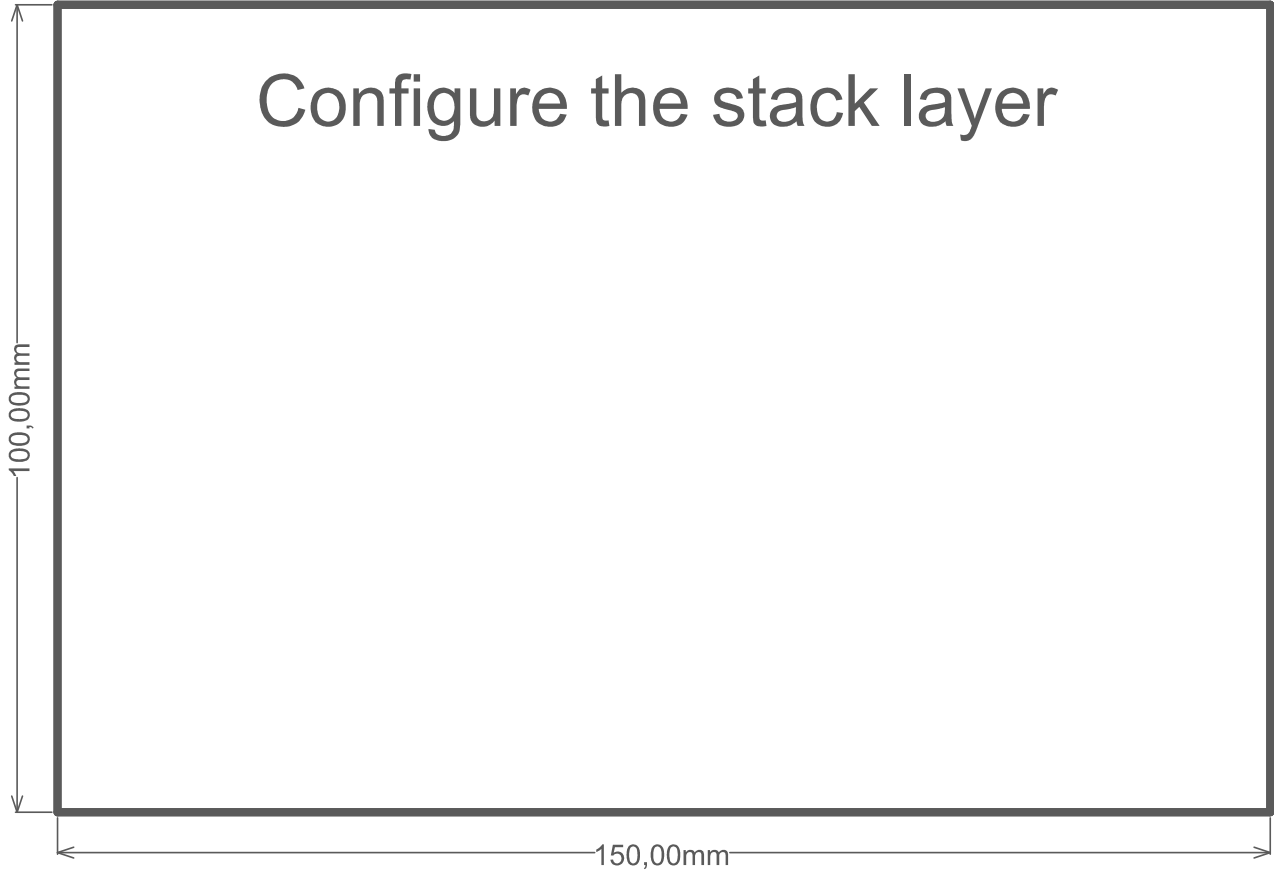
1

2

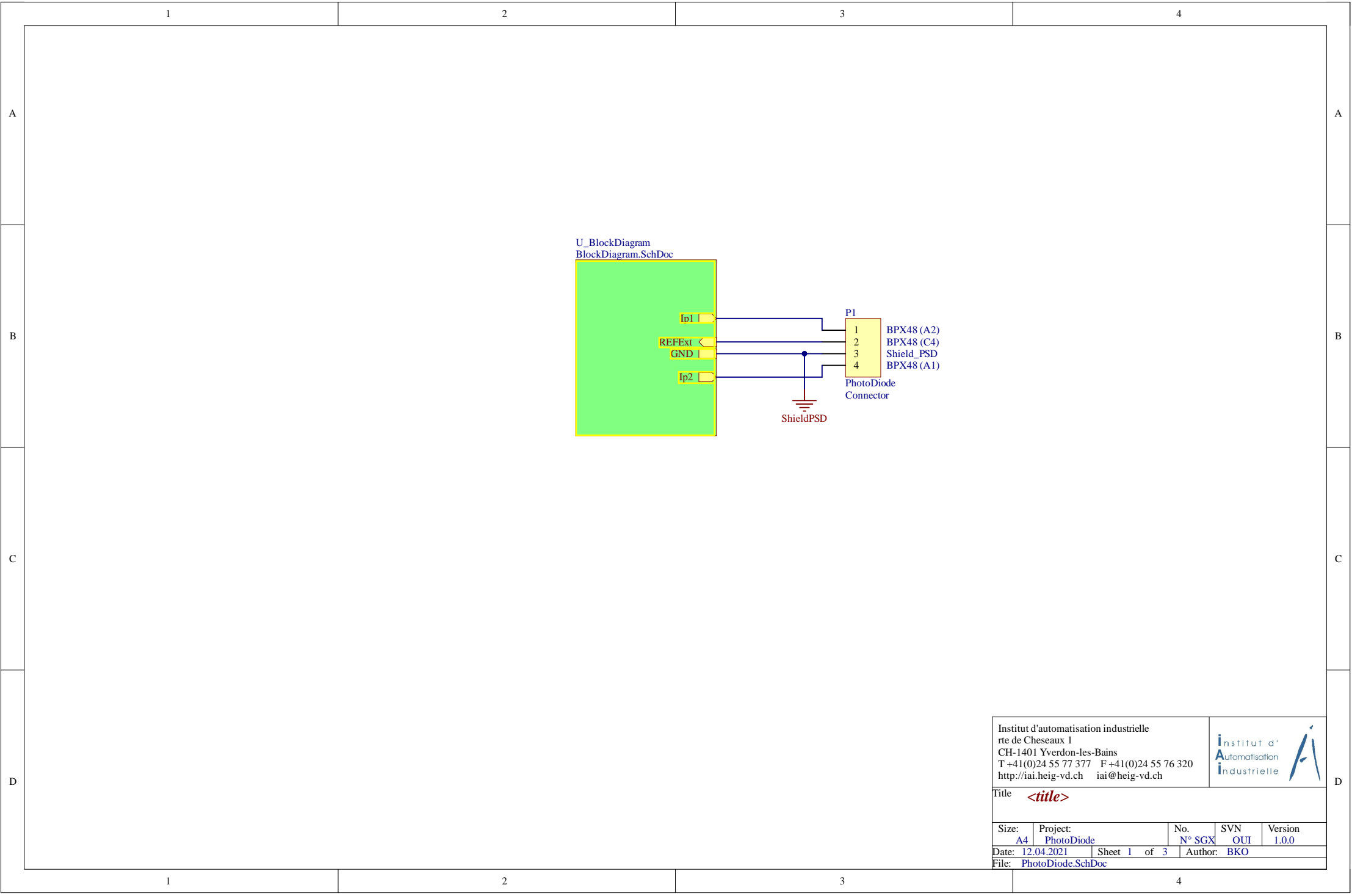
3

4

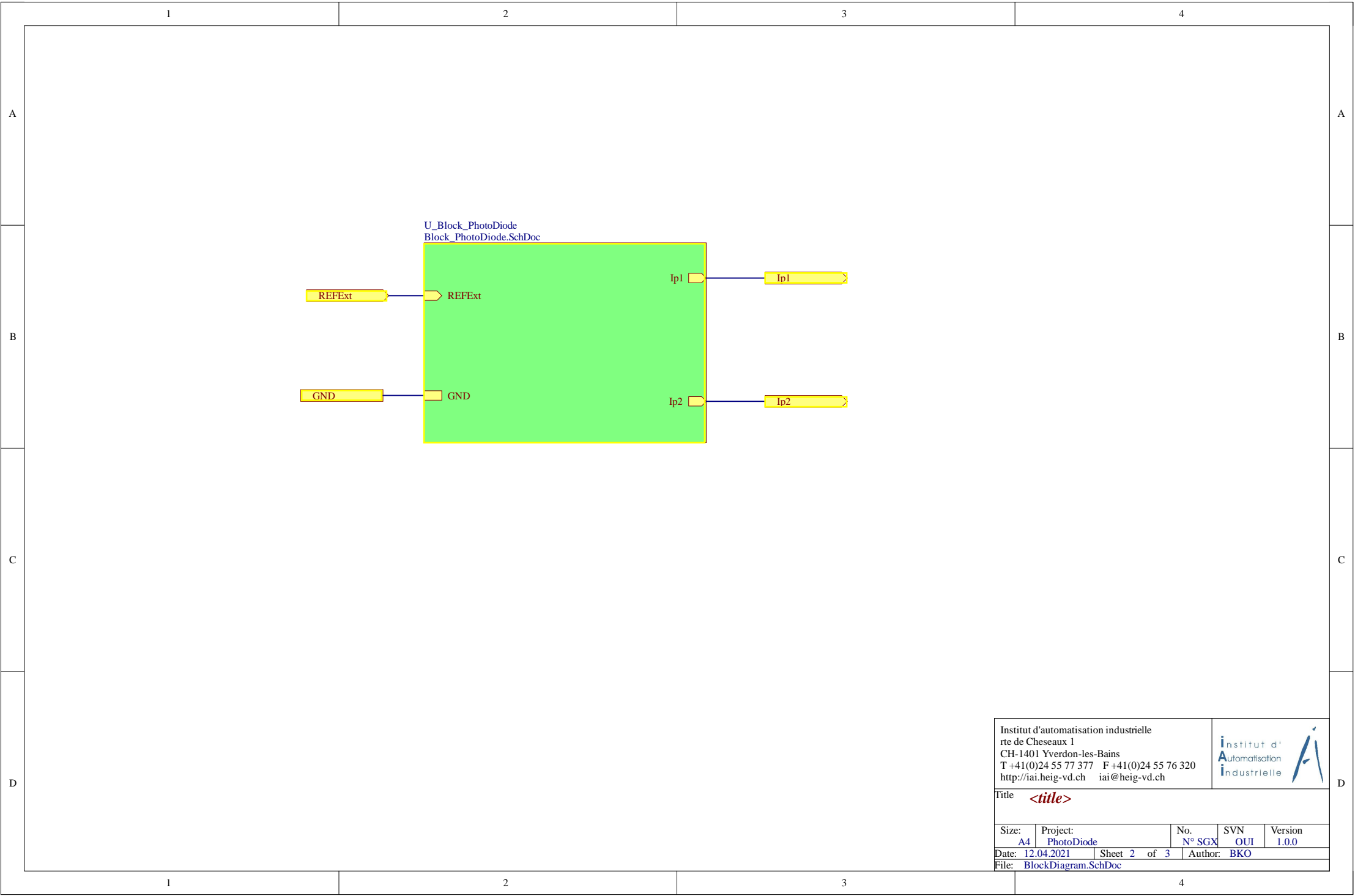
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
	Top Surface Finish	Nickel, Gold	0.020mm		
	Top Layer	CF-004	0.035mm		
1	Dielectric 1	PP-017	0.129mm	4,3	
	Dielectric 2	PP-017	0.129mm	4,3	
2	Int1 (GND)	CF-004	0.035mm		
	Dielectric 3	Core-039	0.711mm	4,8	
3	Int2 (PWR)	CF-004	0.035mm		
	Dielectric 4	PP-017	0.129mm	4,3	
	Dielectric 5	PP-017	0.129mm	4,3	
4	Bottom Layer	CF-004	0.035mm		
	Bottom Surface Finish	Nickel, Gold	0.020mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				



Comment	Description	Designator	Footprint	LibRef	Quantity
LED	LED	LED	MicroMatch4p	MicroMatch4p	1







1

2

3

4

A

A

B


B

C

C

D

D

Institut d'automatisation industrielle rte de Cheseaux 1 CH-1401 Yverdon-les-Bains T +41(0)24 55 77 377 F +41(0)24 55 76 320 <a href="http://iai.heig-vd.ch">http://iai.heig-vd.ch</a> <a href="mailto:iai@heig-vd.ch">iai@heig-vd.ch</a>				
Title <i>&lt;title&gt;</i>				
Size: A4	Project: PhotoDiode	No. N° SGX	SVN OUI	Version 1.0.0
Date: 12.04.2021	Sheet 3 of 3	Author: BKO		
File: <a href="#">Block_PhotoDiode.SchDoc</a>				

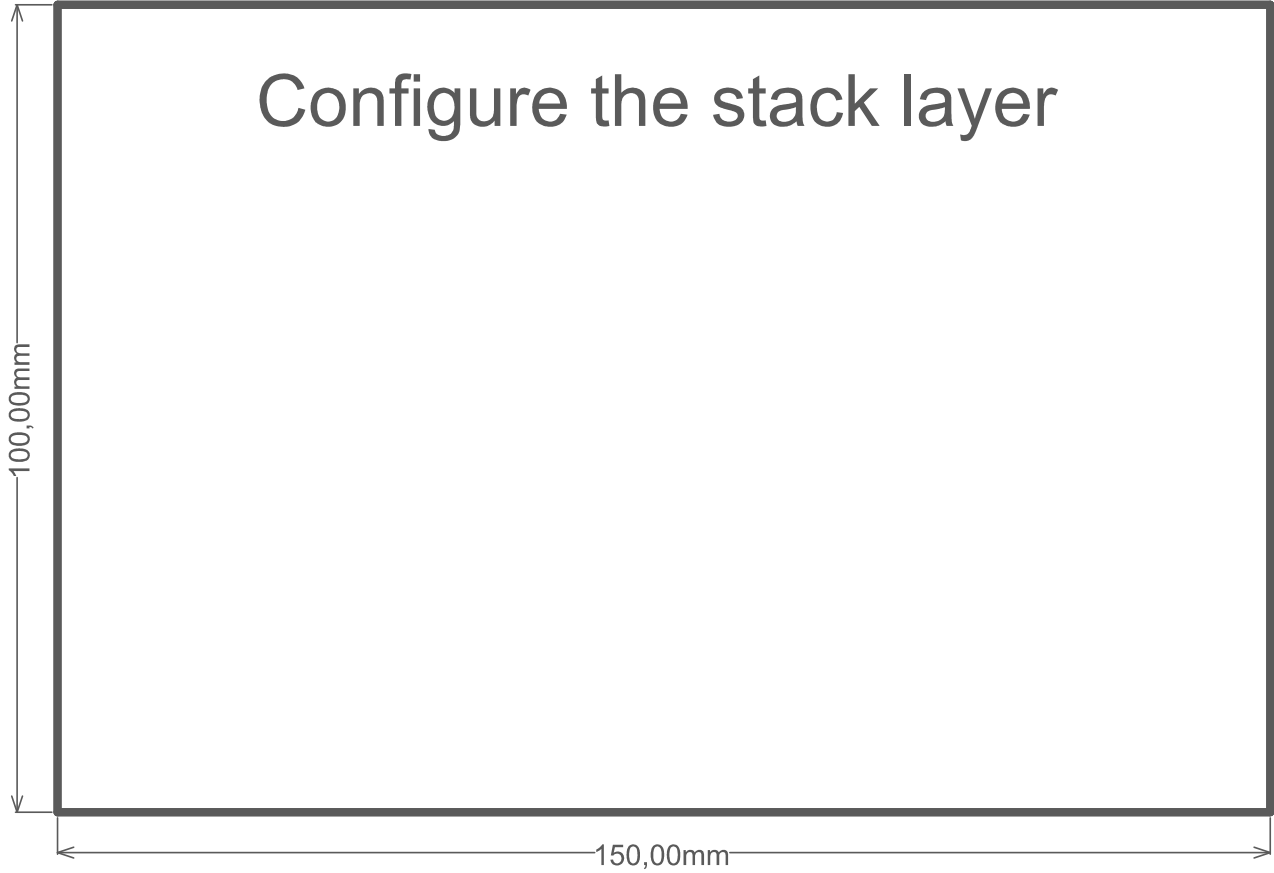
1

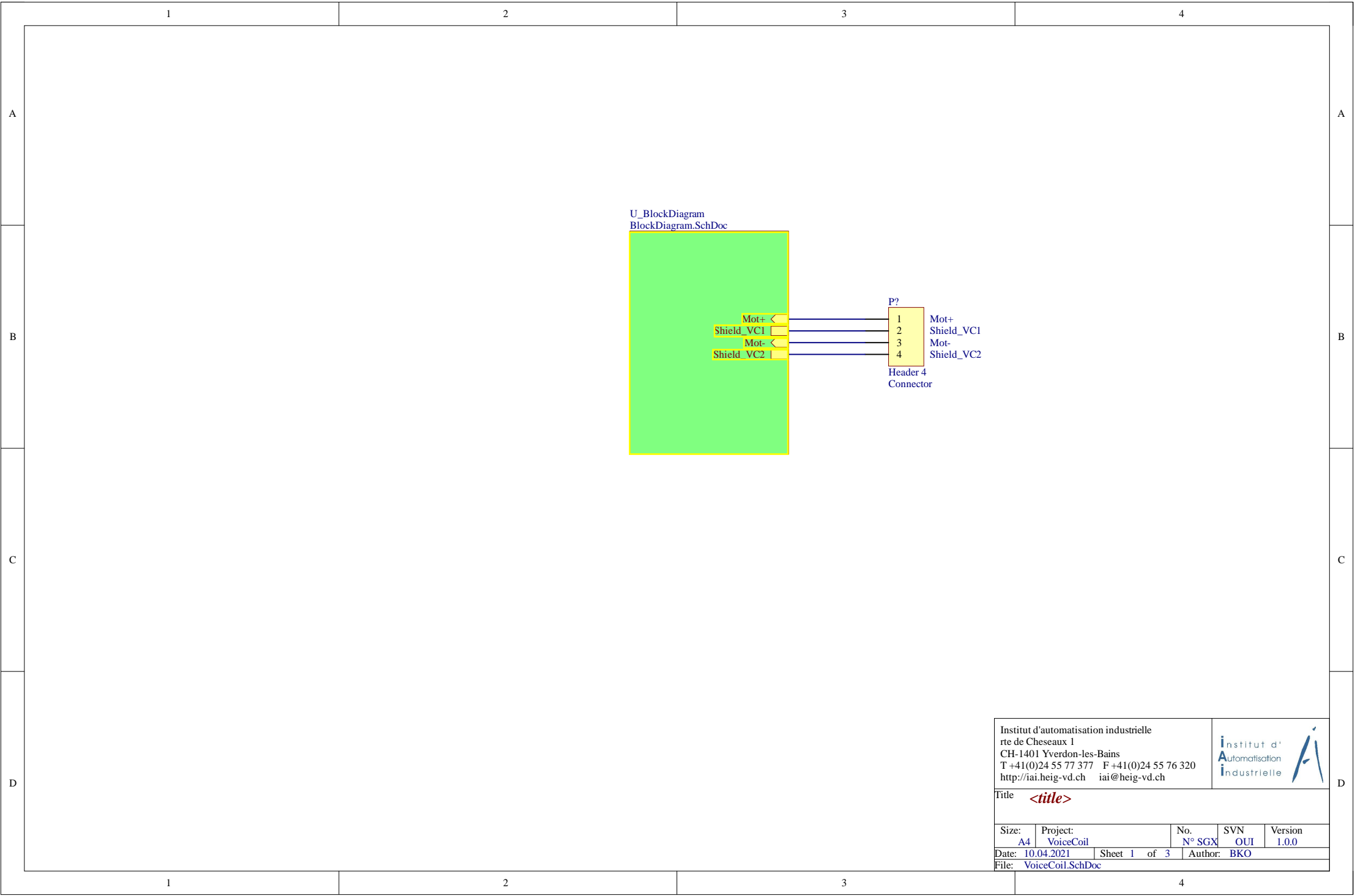
2

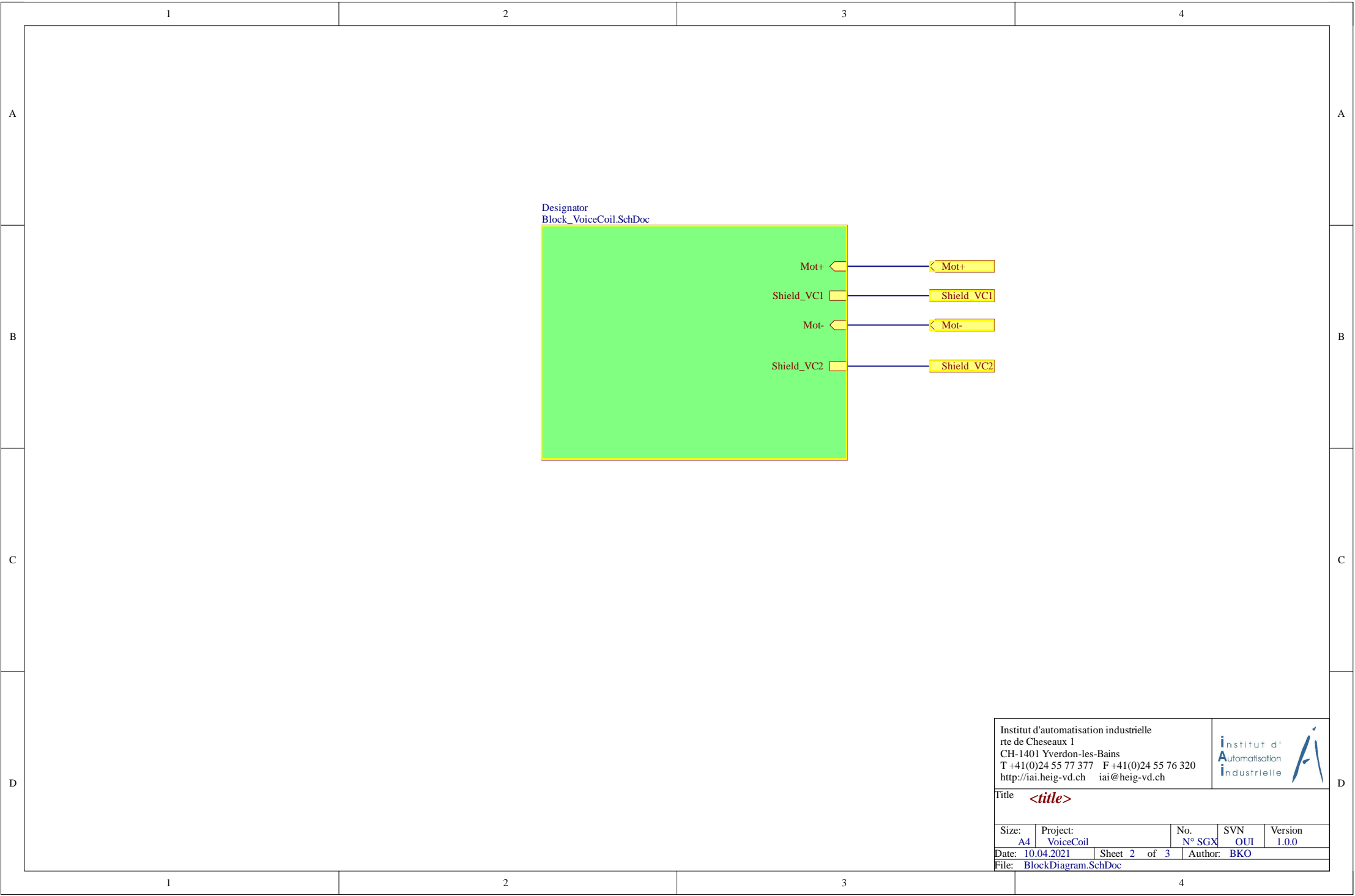
3

4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
	Top Surface Finish	Nickel, Gold	0.020mm		
1	Top Layer	CF-004	0.035mm		
	Dielectric 1	PP-017	0.129mm	4,3	
	Dielectric 2	PP-017	0.129mm	4,3	
2	Int1 (GND)	CF-004	0.035mm		
	Dielectric 3	Core-039	0.711mm	4,8	
	Int2 (PWR)	CF-004	0.035mm		
3	Dielectric 4	PP-017	0.129mm	4,3	
	Dielectric 5	PP-017	0.129mm	4,3	
	Bottom Layer	CF-004	0.035mm		
	Bottom Surface Finish	Nickel, Gold	0.020mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				







1

2

3

4

A

A

B

B

C


C

D

D

Institut d'automatisation industrielle  
rte de Cheseaux 1  
CH-1401 Yverdon-les-Bains  
T +41(0)24 55 77 377 F +41(0)24 55 76 320  
<http://iai.heig-vd.ch> [iai@heig-vd.ch](mailto:iai@heig-vd.ch)

institut d'  
Automatisation  
industrielle



Title <title>

Size: A4	Project: VoiceCoil	No. N° SGX	SVN OUI	Version 1.0.0
Date: 10.04.2021	Sheet 3 of 3	Author: BKO		
File: Block_VoiceCoil.SchDoc				

1

2

3

4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
	Top Surface Finish	Nickel, Gold	0.020mm		
	Top Layer	CF-004	0.035mm		
1	Dielectric 1	PP-017	0.129mm	4,3	
	Dielectric 2	PP-017	0.129mm	4,3	
2	Int1 (GND)	CF-004	0.035mm		
	Dielectric 3	Core-039	0.711mm	4,8	
3	Int2 (PWR)	CF-004	0.035mm		
	Dielectric 4	PP-017	0.129mm	4,3	
	Dielectric 5	PP-017	0.129mm	4,3	
4	Bottom Layer	CF-004	0.035mm		
	Bottom Surface Finish	Nickel, Gold	0.020mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

